



Product Change Notification

CN-202203039F

Issue date: 08 Jul
2022

**Effective
date:** 09 Jan 2023

Dear
data@mouser.co
m,

Here's your
personalized
quality
information
concerning
products our
customers and
partners
purchased from
Nexperia.

For more details
please contact
your respective
Nexperia
CSR/AM.



Transfer TSSOP5/6 Picogate (-Q100) automotive products into zero delamination package on mature Strip to Strip production platform in ATSN (Nexperia Malaysia)

Change Category

☐ Wafer Fab Process	☒ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☒ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage

Details of this change

Transfer TSSOP5/6 Picogate automotive products from reel to reel into mature Strip to Strip (StS) production platform to achieve zero delamination

- Improve intrinsic package quality by transfer production to mature StS platform with enhanced mould compound
- Expand assembly production capacity Picogate TSSOP5/6
- BOM change for zero delamination performance

- No change in diffusion fab and assembly location

Qualification in accordance to the Automotive Electronics Council:

- AEC-Q100-rev. H Stress Test Qualification for Integrated Circuits
- AEC-Q006-rev. A Qualification requirements for Cu-wire interconnection

SQR_CN-202203039F.pdf: https://qcm.nexperia.com/Document/DOC-541129/SQR_CN-202203039F.pdf

Why do we implement this change?

- To improve the intrinsic package/product quality
- Introduce 0 delam package for TSSOP5/6 Picogate automotive products
- To support increased customer demand
- Order Lead-Time Improvement

Identification of affected products

The changed products can be identified by backward traceability of the product marking date code as well as on the reel and box labels

Management summary

Transfer TSSOP5/6 Picogate automotive (-Q100) products into zero delamination package on mature Strip to Strip production platform in ATSN (Nexperia Malaysia)

Product availability

Production

Planned first shipment: 01 Jan 2023

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 07 Aug 2022. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Remarks

- No change in form, fit, function, quality or reliability anticipated. - No impact on the product's functionality anticipated. - No change in die (same electrical distribution). - No change in data sheet and test limits. - No change in ordering code 12NC (sales part number). - Samples are available upon request via Helpdesk+ from BG Analog & Logic ICs sample store in Nijmegen The Netherlands.

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

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